

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5092406

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JAMES A. SACK	05/08/2008
DR. MOHIT K. BHATNAGAR	05/08/2008
JACK Y. YEH	05/08/2008
RECEIVING PARTY DATA	
Name:	JMEA CORPORATION
Street Address:	1 RESEARCH COURT
Internal Address:	SUITE 450
City:	ROCKVILLE
State/Country:	MARYLAND
Postal Code:	20850
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16055398
CORRESPONDENCE DATA	
Fax Number:	(301)365-9101
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(301)365-9040
Email:	mail@plumsea.com
Correspondent Name:	PLUMSEA LAW GROUP, LLC
Address Line 1:	6710 A ROCKLEDGE DRIVE
Address Line 2:	SUITE 400
Address Line 4:	BETHESDA, MARYLAND 20817
ATTORNEY DOCKET NUMBER:	39-1082
NAME OF SUBMITTER:	STEVEN P. ARNHEIM
SIGNATURE:	/Steven P. Arnheim/
DATE SIGNED:	08/10/2018
Total Attachments: 2	
source=2018-08-10_39-1082_Assignment#page1.tif	
source=2018-08-10_39-1082_Assignment#page2.tif	

ASSIGNMENT

WHEREAS, James A. Sack, a citizen of the United States of America, residing at Elverson, Pennsylvania, U.S.A.; Dr. Mohit K. Bhatnagar, a citizen of the United States of America, residing at Potomac, Maryland, U.S.A.; and Jack Y. Yeh, a citizen of the United States of America, residing at North Potomac, Maryland, U.S.A.; hereinafter (collectively) referred to as the Assignor, have invented certain new and useful improvements in
DISK FUSION IMPLANT

for which an application for Letters Patent of the United States has been prepared,

- the Declaration for said application executed on even date herewith;
- said application having been filed in the United States Patent and Trademark Office on _____ and accorded Serial Number _____, and was amended on _____ (if applicable);
- said application having been filed under the Patent Cooperation Treaty on _____ and accorded Application No. _____, the United States of America being designated;

WHEREAS, JMEA Corporation
1 Research Court
Suite 450
Rockville, MD 20850
U.S.A.

is desirous of acquiring the entire right, title and interest in and to the aforesaid invention and in and to any Letters Patent of the United States or any foreign country which may be granted therefor;

NOW THEREFORE, for good and valuable consideration the Assignor by these presents do sell, assign, and transfer unto the Assignee, its successors, legal representatives and assigns, the full and exclusive right to the invention as described in said application, and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations and extensions thereof;

AND said Assignor authorizes and requests the Commissioner of Patents and Trademarks or any other proper officer or agency of any country to issue all said Letters Patent to said Assignee;

AND said Assignor warrants and covenants that I/We have full right to convey the entire interest herein assigned and that I/We have not executed and will not execute any instrument or assignment in conflict herewith;

AND said Assignor agrees to communicate to said Assignee or its representatives any facts known to me/us respecting said invention, to execute all divisional, continuation, reissue and foreign applications, sign all lawful documents and make all rightful oaths relating to said invention, and to testify in any judicial or administrative proceeding and generally do everything possible to aid the said Assignee to obtain and enforce said Letters Patent in the United States or any foreign country when requested so to do by said Assignee.

IN WITNESS WHEREOF, I/We have hereunto set my/our hand and seal.

Date: 5/8/08

Signature: James A. Sack
Name: James A. Sack

Date: _____

Signature: _____
Name: Dr. Mohit K. Bhatnagar

Date: _____

Signature: _____
Name: Jack Y. Yeh

ASSIGNMENT

WHEREAS, James A. Sack, a citizen of the United States of America, residing at Elverson, Pennsylvania, U.S.A.; Dr. Mohit K. Bhatnagar, a citizen of the United States of America, residing at Potomac, Maryland, U.S.A.; and Jack Y. Yeh, a citizen of the United States of America, residing at North Potomac, Maryland, U.S.A.; hereinafter (collectively) referred to as the Assignor, have invented certain new and useful improvements in

DISK FUSION IMPLANT

for which an application for Letters Patent of the United States has been prepared,

- the Declaration for said application executed on even date herewith;
- said application having been filed in the United States Patent and Trademark Office on _____ and accorded Serial Number _____, and was amended on _____ (if applicable);
- said application having been filed under the Patent Cooperation Treaty on _____ and accorded Application No. _____, the United States of America being designated;

WHEREAS, JMEA Corporation
1 Research Court
Suite 450
Rockville, MD 20850
U.S.A.

is desirous of acquiring the entire right, title and interest in and to the aforesaid invention and in and to any Letters Patent of the United States or any foreign country which may be granted therefor;

NOW THEREFORE, for good and valuable consideration the Assignor by these presents do sell, assign, and transfer unto the Assignee, its successors, legal representatives and assigns, the full and exclusive right to the invention as described in said application, and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations and extensions thereof;

AND said Assignor authorizes and requests the Commissioner of Patents and Trademarks or any other proper officer or agency of any country to issue all said Letters Patent to said Assignee;

AND said Assignor warrants and covenants that I/We have full right to convey the entire interest herein assigned and that I/We have not executed and will not execute any instrument or assignment in conflict herewith;

AND said Assignor agrees to communicate to said Assignee or its representatives any facts known to me/us respecting said invention, to execute all divisional, continuation, reissue and foreign applications, sign all lawful documents and make all rightful oaths relating to said invention, and to testify in any judicial or administrative proceeding and generally do everything possible to aid the said Assignee to obtain and enforce said Letters Patent in the United States or any foreign country when requested so to do by said Assignee.

IN WITNESS WHEREOF, I/We have hereunto set my/our hand and seal.

Date: _____

Signature: _____

Name: James A. Sack

Date: 5/8/08

Signature: Mohit K. Bhatnagar
Name: Dr. Mohit K. Bhatnagar

Date: 5/8/08

Signature: Jack Y. Yeh
Name: Jack Y. Yeh

PATENT